Method and Assembly for Wafer Positioning Inspection

ABSTRACT

A method of inspecting wafer positioning on a plate unit, the method comprising, providing an inspection tool on the plate unit; transferring an inspection wafer onto the plate unit with the inspection tool on the plate unit; and inspecting the wafer positioning based on whether an alignment element of the inspection tool mates with a corresponding alignment element of the inspection wafer when the inspection wafer is transferred onto the plate unit.

FIG. 1